ASSOCIATION CONNECTI ELECTRONICS INDUSTRI	© Copyright 2005, IPC, H	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowelevel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Tyj Distribute													
upplier Infori	mation														
Company name*			Company un	Company unique ID			Unique ID Authority				Respons	Response Date*			
nsemi											2025-05-	2025-05-03			
				Title - Contact			Phone - Contact*				Email - 0	Email - Contact*			
Product-Env-Stew	vards		Product Enviro Compliance			1	NA				Product	Product-Env-Stewards@onsemi.com			
uthorized Repres	sentative*	Title - Representative			P	Phone - Representative*				Email - 1	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product	Product-Env-Stewards@onsemi.com			
Reques	ster Item Number	Mfr Item	em Number Mfr Item Name				Effective Date	Version	Ma	Manufacturing Site		Veight*	UOM	Unit Type	
	FSTD162		6211MTDX 24 BIT BUS SWITCH		TTCH		2025-05-03		PH	PH4		23.028	mg	Each	
<b>Ianufacturing</b>	g Proccess Information							1	1				·	·	
Termina	Terminal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MS	L Rating	Peak Process Body Temperature Max 7		Max Time at Pe	me at Peak Temperature N		Number of Reflow Cycles			
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		) (no Cl	CU Alloy 2		2		260	C		30		ds 3			
Comments		•										•			
TTENTION: MS	SL 2 Rated item requires Dry	y Pack (af	fter electrical	test)											
or more informat	tion regarding material com	position n	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is trought in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.05	mg	Supplier	Silicon (Si)	7440-21-3		2.05	mg
Die Attach	0.255	mg	Supplier	Silver (Ag)	7440-22-4		0.1912	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.0637	mg
Lead Frame	85.28		Supplier	Silver (Ag)	7440-22-4		0.938	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.128	mg
			Supplier	Silicon (Si)	7440-21-3		0.554	mg
			В	Nickel (Ni)	7440-02-0		2.56	mg
			Supplier	Copper (Cu)	7440-50-8		81.1	mg
Mold Compound-Black	125.9	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.59	mg
			Supplier	Carbon Black (C)	1333-86-4		1.259	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		112.051	mg
Plating	8.153	mg	Supplier	Palladium (Pd)	7440-05-3		0.228	mg
			В	Nickel (Ni)	7440-02-0		7.77	mg
			Supplier	Gold (Au)	7440-57-5		0.155	mg
Wire Bond - Au	1.39	mg	Supplier	Gold (Au)	7440-57-5		1.39	mg